g GE Energy	**Functional Testing Specification**
Parts & Repair Services ***Louisville, KY***	**LOU-GED-IS200EXCS**

Test Procedure for a IS200EXCS card

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	G. Chandler	11/16/2012
B			
C			

PREPARED BY	REVIEWED BY	REVIEWED BY	QUALITY APPROVAL
G. Chandler			Charlie Wade
DATE	**DATE**	**DATE**	**DATE**
11/16/2012			11/16/2012

1. SCOPE

1.1 This is a functional testing procedure for a IS200EXCS card

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning
4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
4.2 Equipment Inspection
4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
4.2.1.1 Wires - broken, cracked, or loosely connected
4.2.1.2 Terminal strips / connectors - broken or cracked
4.2.1.3 Components - visually damaged
4.2.1.4 Capacitors - bloated or leaking
4.2.1.5 Solder joints - damaged or cold
4.2.1.6 Circuit board - burned or de-laminated
4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

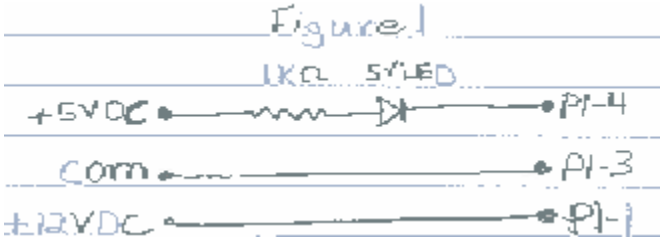
Qty	Reference #	Description
1		Dual Channel Power Supply
1		1K ohm resistor
1		5V LED
1		Small simple magnet
1		Fluke 85 or equivalent

6. Modifications/Upgrades

6.1 Check Orange Book for any modifications or upgrades.

7. Testing Process

7.1 Testing Procedure



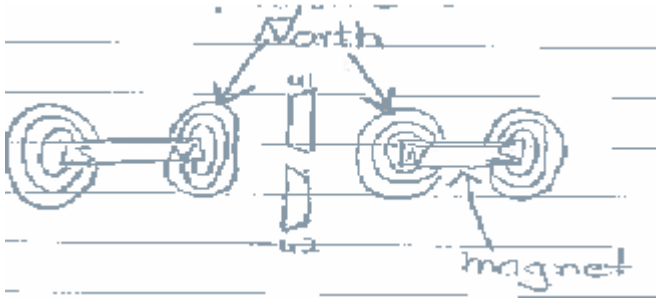
7.1.1 Figure 1

7.1.2 Connect the UUT as per figure 1.

7.1.3 Pass a small magnet in front of one side of the Hall Effect ICs U1 & U2. The LED should light when the magnet is in close proximity to the ICs.

7.1.4 Pass the magnet in front of the other side of the Hall Effect ICs, keeping the orientation of the same pole of the magnet toward the ICs. See figure 2.

7.1.5 Again the LED should light.



7.1.6

7.1.7 Figure 2

7.1.8 Since the Hall Effect ICs are mounted in opposite direction on the PCB, the magnet will turn on one of the ICs when it's on one side and the other IC when it's on the other side.

7.1.9 Using an ohm meter verify 1M ohm +-1% from P1-3 to E1

7.2 ***TEST COMPLETE ***

8. Notes

8.1 None at this time.

9. Attachments

9.1 None at this time.